

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning at page 1, line 21, with the following rewritten paragraph:

-- With the development of electronics industries, a demand for a printed wiring board for mounting an electronic devices such as an IC (integrated circuit) or an LSI (large scale integrated circuit) has suddenly be-increased and a reduction in the size and weight and an increase in the function of an electronic equipment have been required. As a method of mounting electronic devices which meets these requirements, there has recently been employed a mounting method using a film carrier tape such as a TAB tape, a T-BGA tape and an ASIC tape. In particular, the importance has been increased in the electronic industries which use a liquid crystal display (LCD) requiring an enhancement in fineness, a reduction in thickness and a decrease in the frame area of a liquid crystal screen as in a personal computer or the like. --

Please replace the paragraph beginning at page 5, line 13, with the following rewritten paragraph:

-- Fig. 7 shows an example of the structure of ~~the~~ a conventional COF tape. A COF tape 210 has a plurality of sprocket holes 212 and 214 for conveyance of the tape arranged continuously in a longitudinal direction on both side ends in a transverse direction respectively and a device such as an IC is mounted to an almost central portion 216 between the sprocket holes 212 and 214, for example. There is formed a wiring pattern 222 in which an inner lead 218 and an outer lead 220 on the film are connected to each other. --